

DENSE-PAC

MICROSYSTEMS

256 Megabit CMOS DRAM

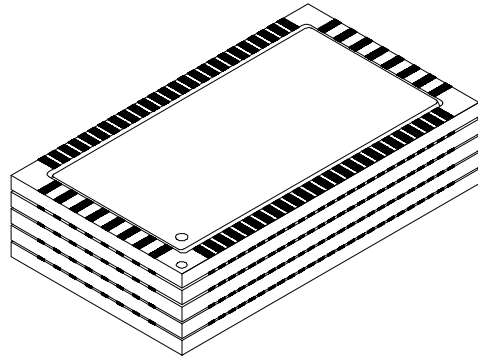
DPnnD8MX32RY5

PRELIMINARY

DESCRIPTION:

The DPnnD8MX32RY5 is the 8 Meg x 32 Dynamic RAM module that utilize the new and innovative space saving TSOP stacking technology. The module is constructed of four 4 Meg x 16 Dynamic RAM's that are configured as 2 banks of 4 Meg x 32.

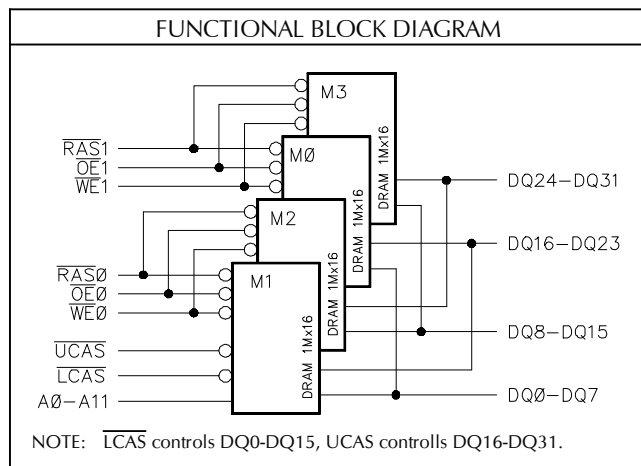
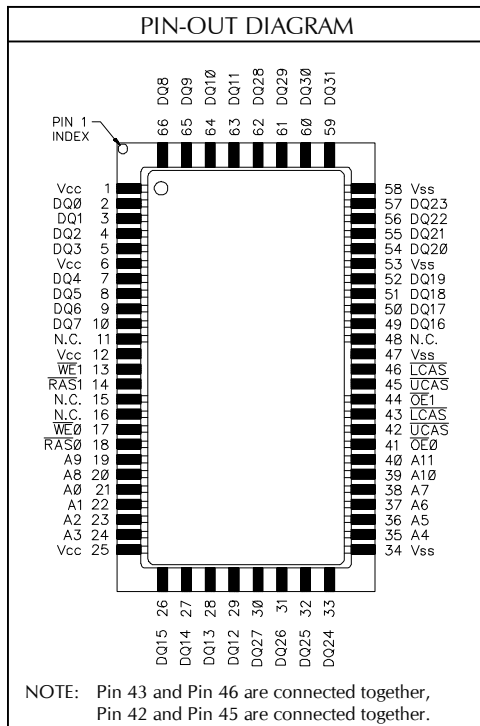
The DPnnD8MX32RY5 provides for a compatible upgrade path to lower density compatible modules. The module features high speed access times, common data inputs and outputs, and three standard refresh modes.



FEATURES:

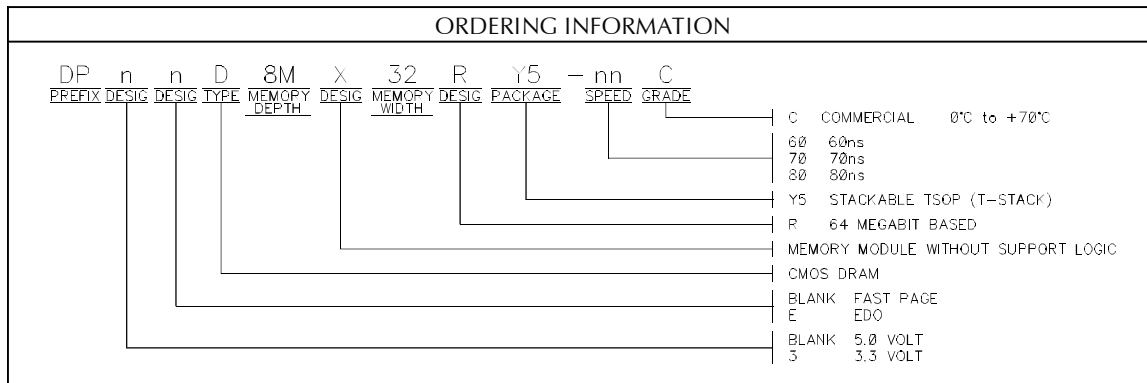
- Access Times: 60, 70, 80ns (max.)
- 5.0V or 3.3V Supply
- Common Data Inputs and Outputs
- EDO or Fast Page Mode Capability
- 4096 Cycles / 64 ms
- 3 Variations of Refresh:
 - \overline{RAS} only Refresh
 - \overline{CAS} before \overline{RAS} Refresh
 - Hidden Refresh
- Package: TSOP Leadless Stack

PIN NAMES	
A0 - A11	Row Address: A0 - A11 Column Address: A0 - A9 Refresh Address: A0 - A11
DQ0 - DQ31	Data In / Data Out
\overline{UCAS}	Upper Column Address Strobe
\overline{LCAS}	Lower Column Address Strobe
$\overline{RAS0} - \overline{RAS1}$	Row Address Enables
$\overline{WE0} - \overline{WE1}$	Data Write Enables
$\overline{OE0} - \overline{OE1}$	Data Output Enables
V _{DD}	Power Supply (+5V)
V _{SS}	Ground
N.C.	No Connect

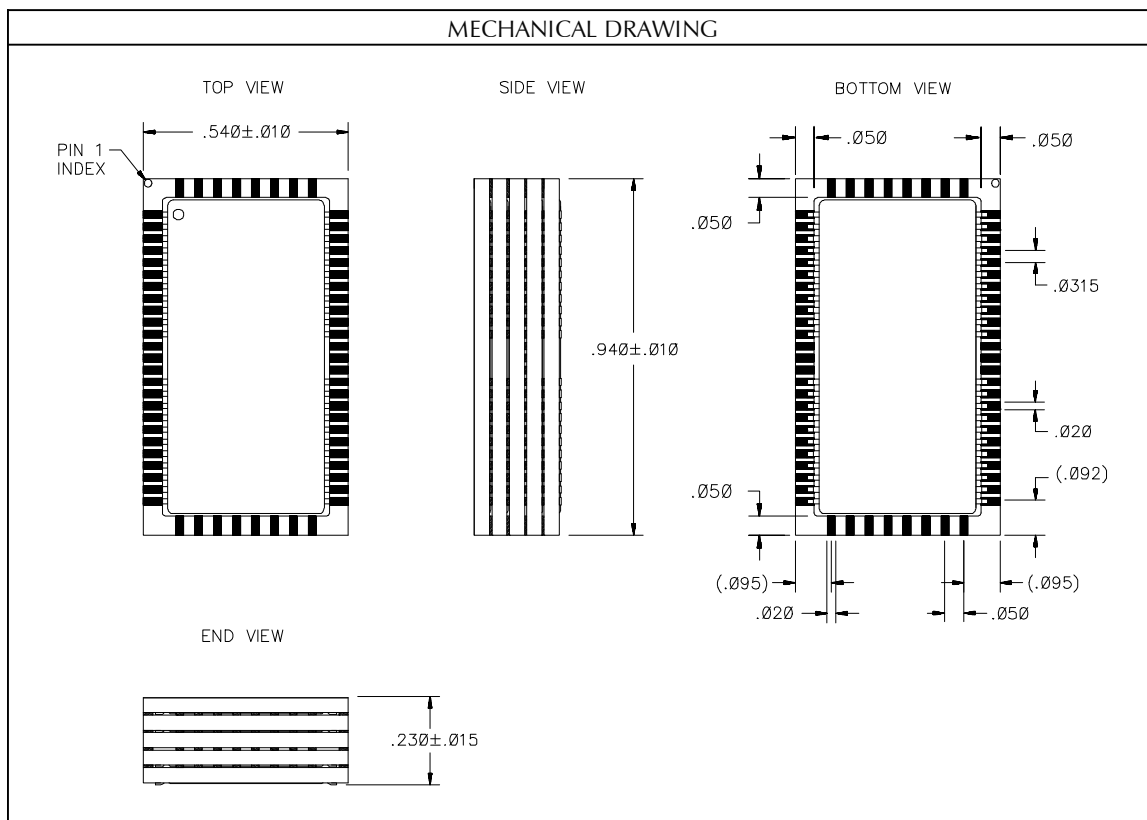


PRELIMINARY

ORDERING INFORMATION



MECHANICAL DRAWING



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